Device and Method for Bonding Substrates

Abstract

The invention relates to a device as well as a corresponding method for producing an electrically conductive direct bond between a bonding side of a first substrate (1) and a bonding side of a second substrate (14) with the following features:

- a workspace (22) that can be closed, gas-tight, against the environment and can be supplied with a vacuum,
- the workspace (22) comprises:
  a) at least one plasma chamber (4) for modifying at least one of the bonding sides and at least one bonding chamber (5) for bonding the bonding sides, and/or
  b) at least one combined bonding/plasma chamber (20) for modifying at least one of the bonding sides and for bonding the bonding sides.

Figure 3.